LM



Schottky Barrier Diode NSR01F30NXT5G

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current. The DSN2 (Dual Silicon No-lead) package is a chip level package using solderable metal contacts under the package similar to DFN style packages. The DSN style package enables 100% utilization of the package area for active silicon, offering a significant performance per board area advantage compared to products in plastic molded packages. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

Features

- Very Low Forward Voltage Drop 370 mV @ 10 mA
- Low Reverse Current 7.0 μA @ 10 V VR
- 100 mA of Continuous Forward Current
- ESD Rating Human Body Model: Class 3B
 - Machine Model: Class C
- Very High Switching Speed
- Low Capacitance CT = 7 pF
- This is a Halide-Free Device
- This is a Pb-Free Device

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

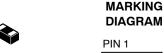
MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Reverse Voltage		V_{R}	30	V
Forward Current (DC)		I _F	100	mA
Forward Surge Current (60 Hz @ 1 cycle)		I _{FSM}	4.0	Α
ESD Rating:	Human Body Model Machine Model	ESD	>8.0 >400	kV V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

30 V SCHOTTKY BARRIER DIODE





DSN2 (0201) CASE 152AA

L = Specific Device Code

M = Month Code

ORDERING INFORMATION

Device	Package	Shipping†
NSR01F30NXT5G	DSN2 (Pb-Free)	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NSR01F30NXT5G

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			400 312	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{0JA} P _D			170 735	°C/W mW
Storage Temperature Range	T _{stg}			-40 to +125	°C
Junction Temperature	TJ			+125	°C

- Mounted onto a 4 in square FR-4 board 10 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
 Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V _R = 10 V) (V _R = 30 V)	I _R			7.0 50	μΑ
Forward Voltage (I _F = 10 mA) (I _F = 100 mA)	V _F			0.37 0.50	٧
Total Capacitance (V _R = 5.0 V, f = 1 MHz)	СТ		7.0		pF

NSR01F30NXT5G

TYPICAL CHARACTERISTICS

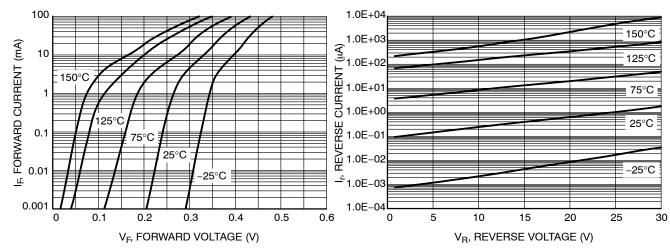


Figure 1. Forward Voltage

Figure 2. Leakage Current

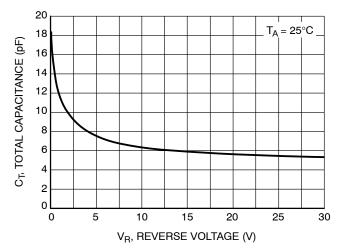


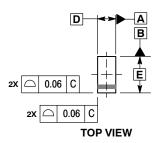
Figure 3. Total Capacitance

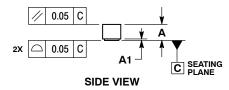


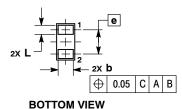


DSN2, 0.6x0.3, 0.4P, (0201) CASE 152AA **ISSUE B**

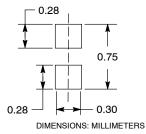
DATE 30 APR 2017







MOUNTING FOOTPRINT*



See Application Note AND8398/D for more mounting details

NOTES

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.24	0.30		
A1	0.00	0.01		
b	0.20	0.22		
D	0.30 BSC			
Е	0.60 BSC			
е	0.40 BSC			
L	0.10	0.12		

GENERIC MARKING DIAGRAM1*

MARKING DIAGRAM2* PIN 1





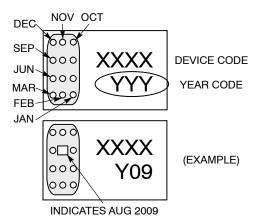
GENERIC

XXXX = Specific Device Code YYY = Year Code

= Specific Device Code Χ = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

CATHODE BAND MONTH CODING



DOCUMENT NUMBER:	98AON39897E	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	DSN2, 0.6X0.3, 0.4P, (0201)		PAGE 1 OF 1	

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries, onsemi reserves brisefin and of 160 m are trademarked so defined values of services and of the confined values and of the values of the confined values and of the values of the confined values and of the values of the v special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales